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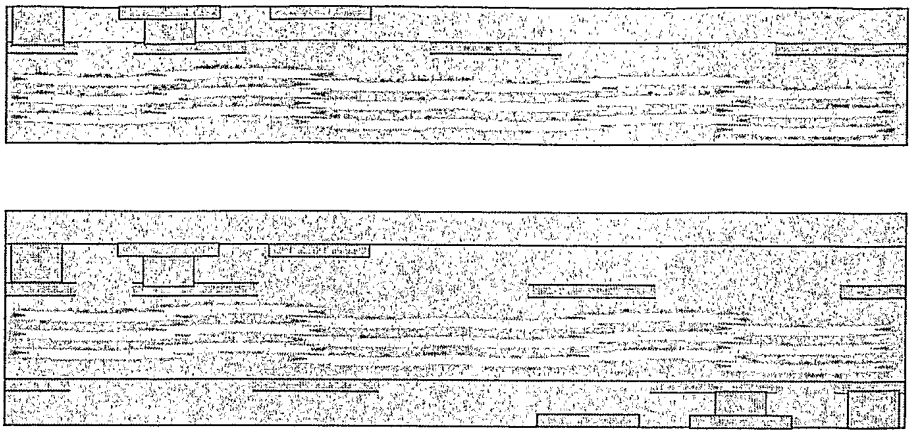
(54) Title: METHOD OF MANUFACTURING A CIRCUIT CARRIER AND THE USE OF THE METHOD



(57) Abstract: A method of manufacturing a circuit carrier and the use of said method are proposed, said method comprising, after providing a printed circuit board (a), coating the circuit board on at least one side thereof with a dielectric (b), structuring the dielectric for producing trenches and vias therein using laser ablation (c) are performed. Next, a primer layer is deposited onto the dielectric, either onto the entire surface thereof or into the produced trenches and vias only (d). A metal layer is deposited onto the primer layer, with the trenches and vias being completely filled with metal for forming conductor structures therein (e). Finally, the excess metal and the primer layer are removed until the dielectric is exposed if the primer layer was deposited onto the entire surface thereof, with the conductor structures remaining intact (f).

WO 2005/076681 A1